



IBM Research

Future Design Systems for Large Chips

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IBM T J Watson Research Center

Outline

- **Trends**
 - Business
 - Technology
 - System
- **Impact on Design Systems**
- **Summary**

Business Trends

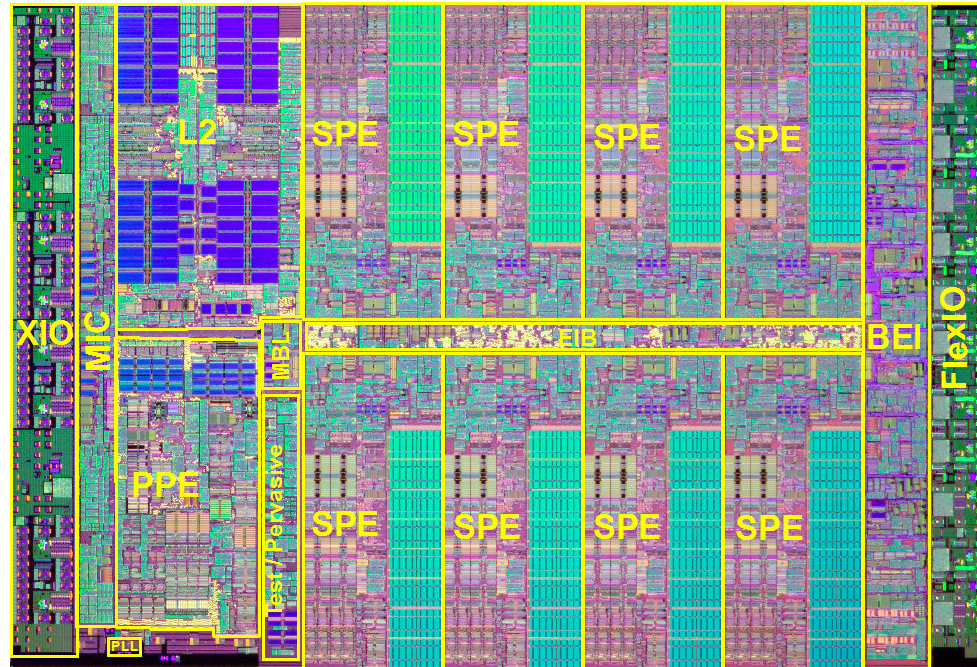
- **Information technology business is growing again**
- **Companies re-engineering their business**
 - Pervasive networking
 - Ubiquitous sensors
 - Affordable computation
 - Open standards
- **Innovative solutions provide competitive advantage**

Growing Demands on System Designer

- **Exploit**
 - Increasing parallelism
 - Low latency communication
 - Accelerators for critical tasks

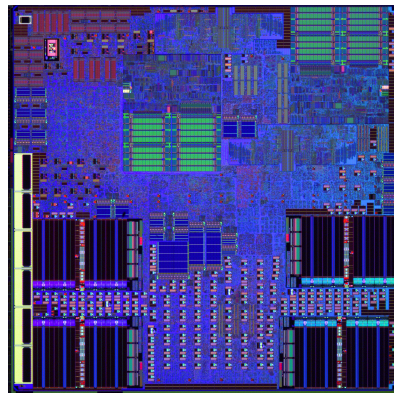
- **Offer**
 - Scalable systems for growth
 - Reliable services and storage
 - Affordable cost of ownership

Innovative Architecture Example 1 – Cell Processor



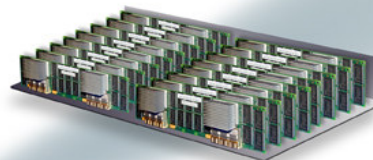
- IBM, Sony and Toshiba partnership
- 64-bit Power Architecture™ (PPE)
- 8 Synergistic Processor Elements (SPE)

Innovative Architecture Example 2 – Blue Gene/L



700 Mhz SoC

Node Card
32 chips

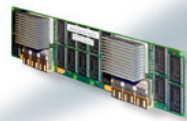


Compute Card
2 chips

90/180 GF/s
16 GB

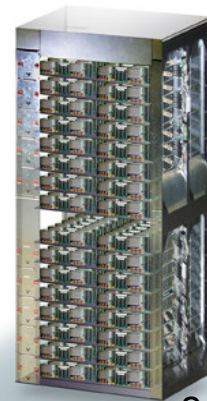
Chip
2 processors

2.8/5.6 GF/s
4 MB



5.6/11.2 GF/s
1.0 GB

Rack
32 Node Cards



2.8/5.6 TF/s
512 GB

System
64 Racks, 64x32x32 chips

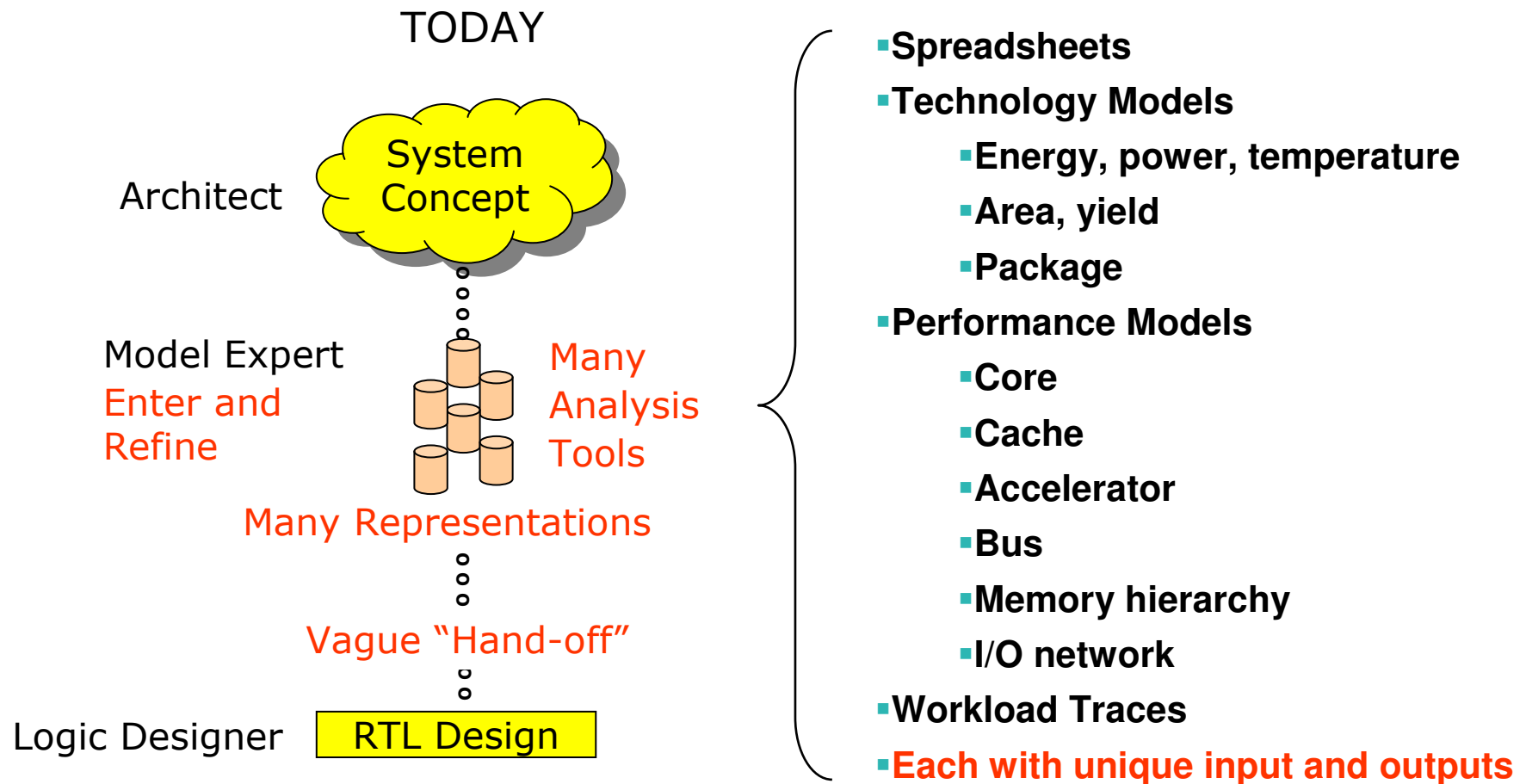


180/360 TF/s
32 TB

System Design Becoming More Complex

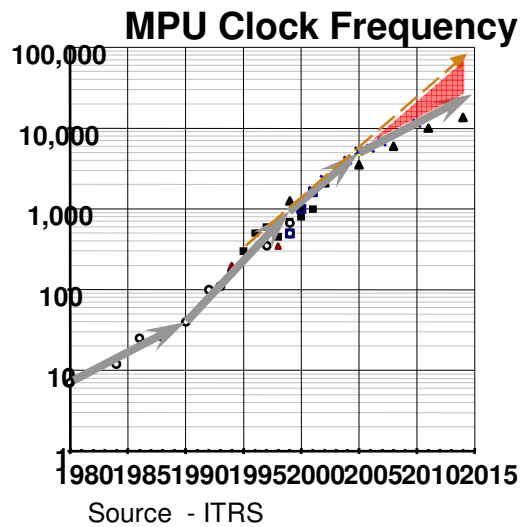
- **Complex tradeoffs – power, performance, interconnect**
- **Evolving and future workloads**
- **New software architectures**
- **Done by a few experienced experts**
- **Tools are spreadsheets and custom models**

Need to Extend DA to System Design Craft

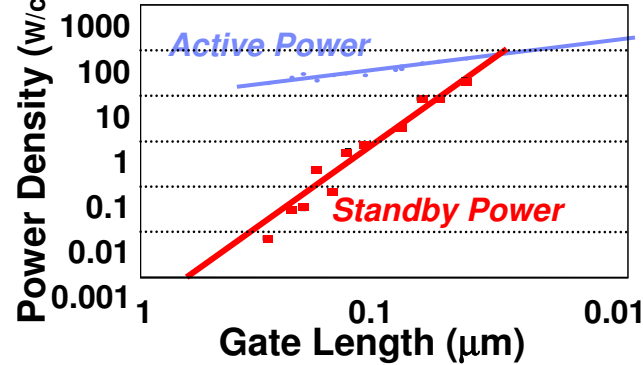


Growing Technology Challenges

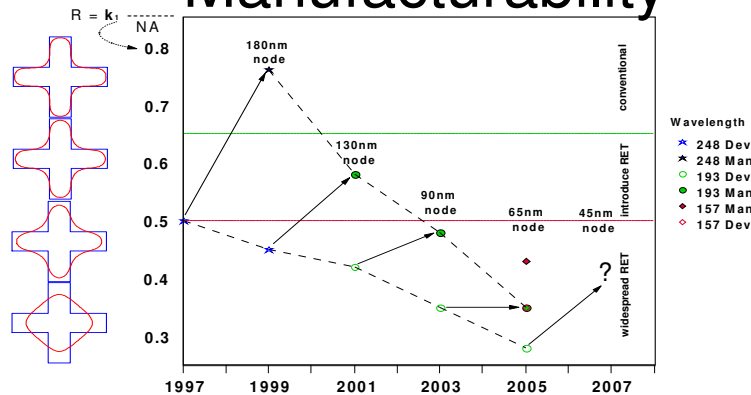
Performance



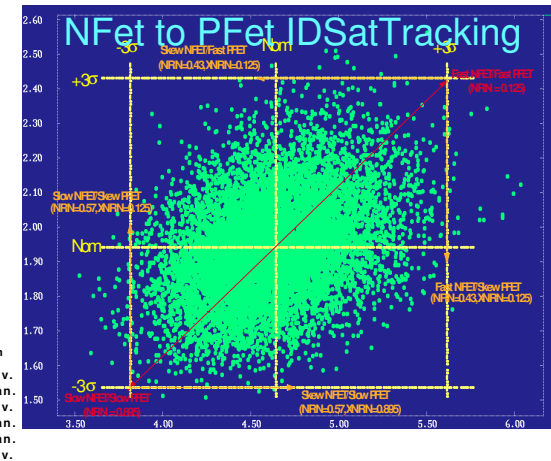
Power Management



Manufacturability

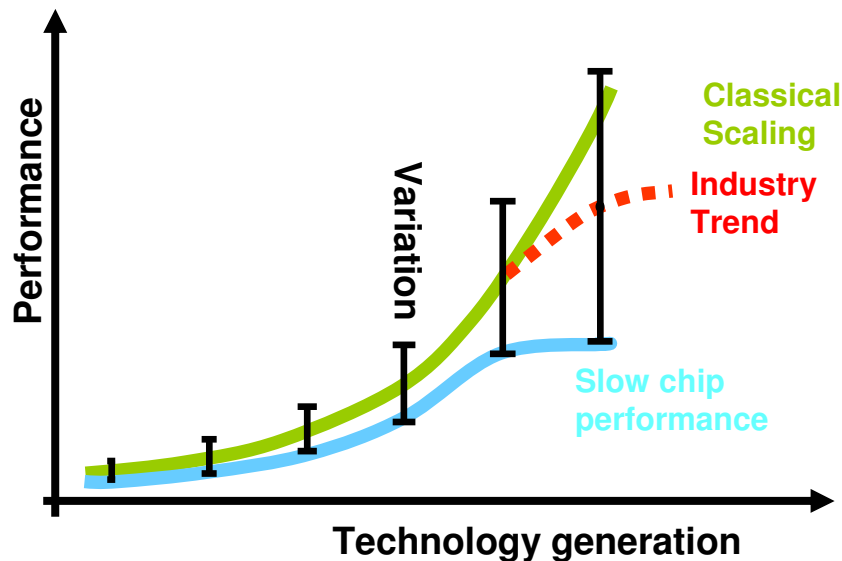


Variability

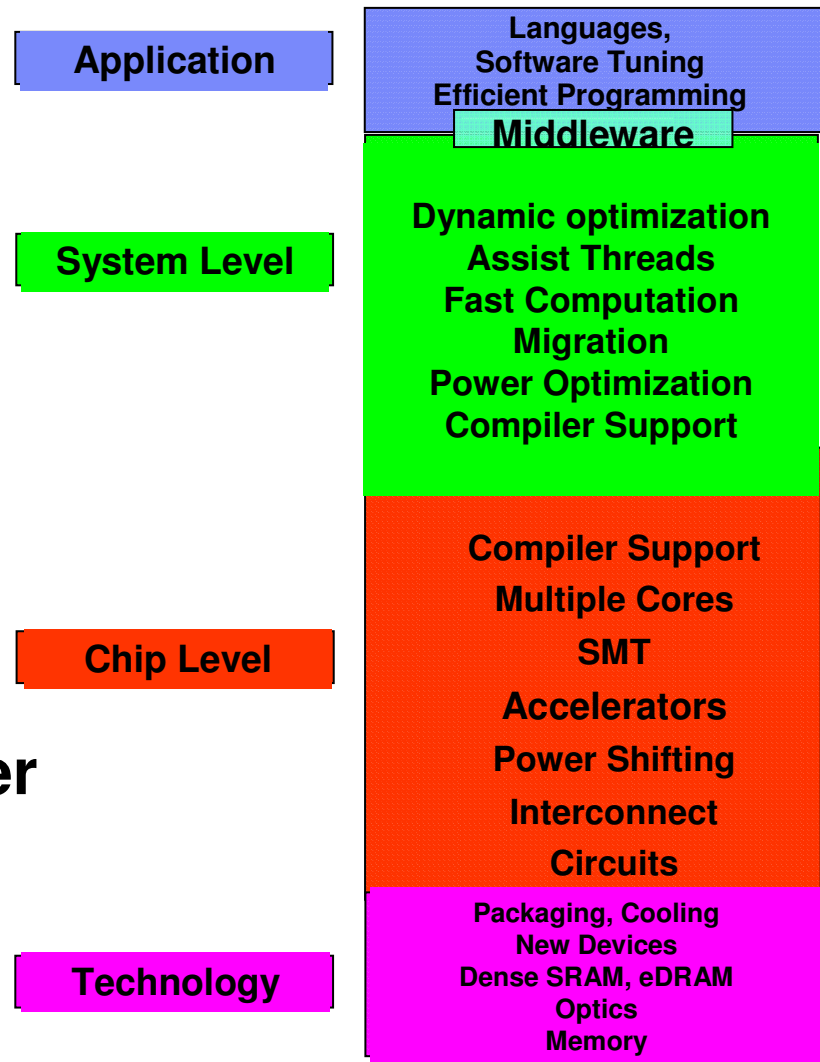


Time

Systems Performance – An Integrated Approach



- Frequency no longer dominant performance driver
- Advances will come from entire performance stack

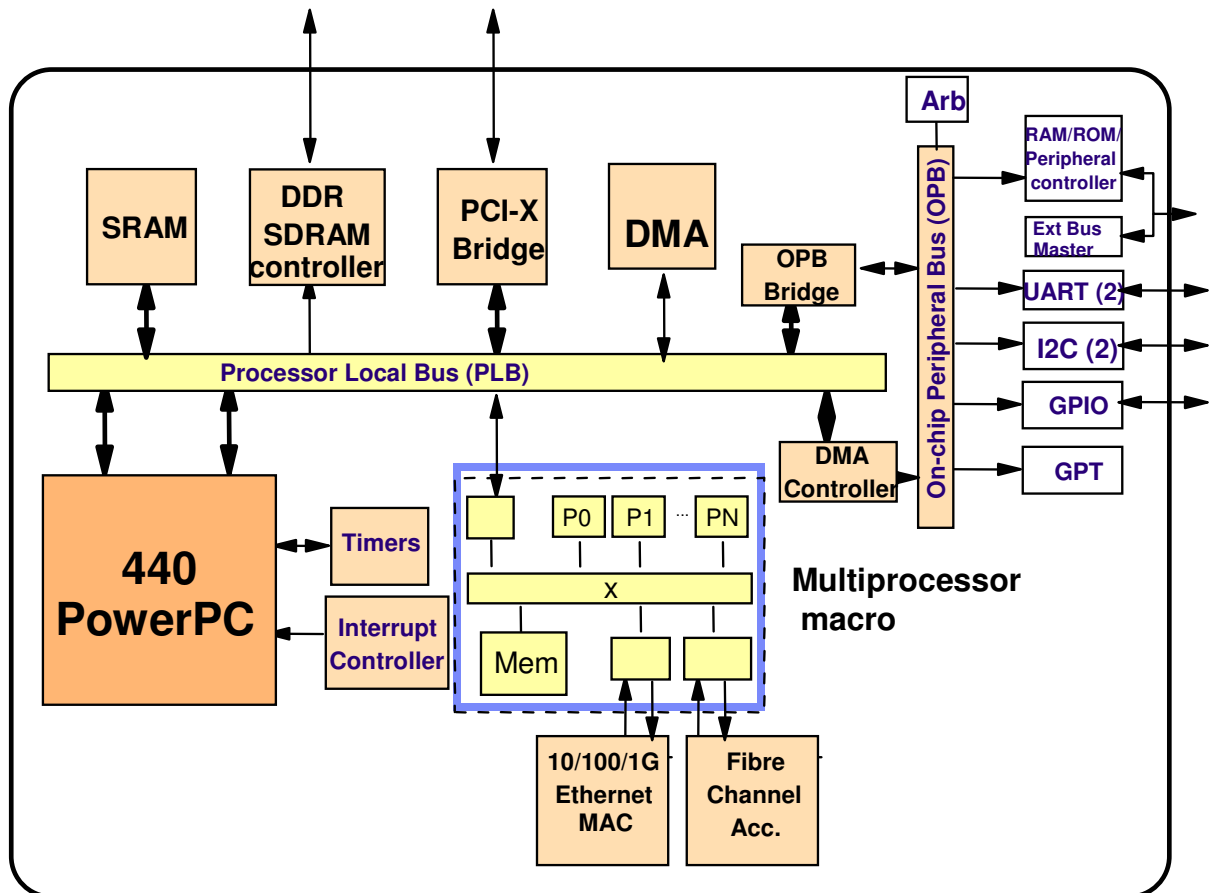


Complex Hardware Tradeoffs

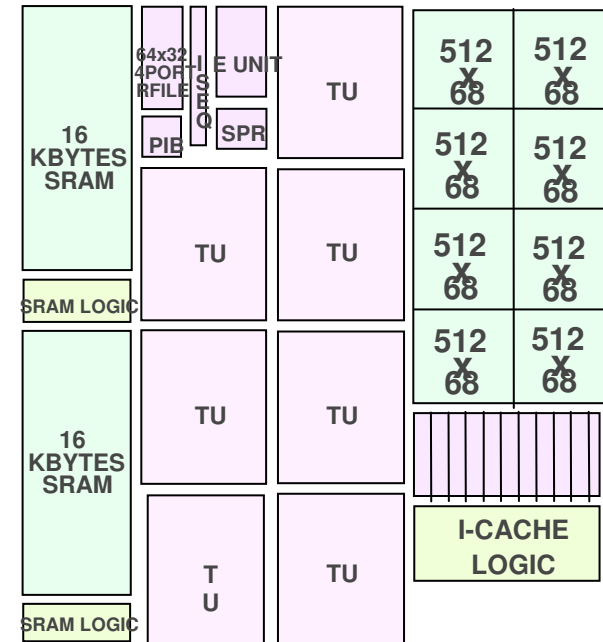
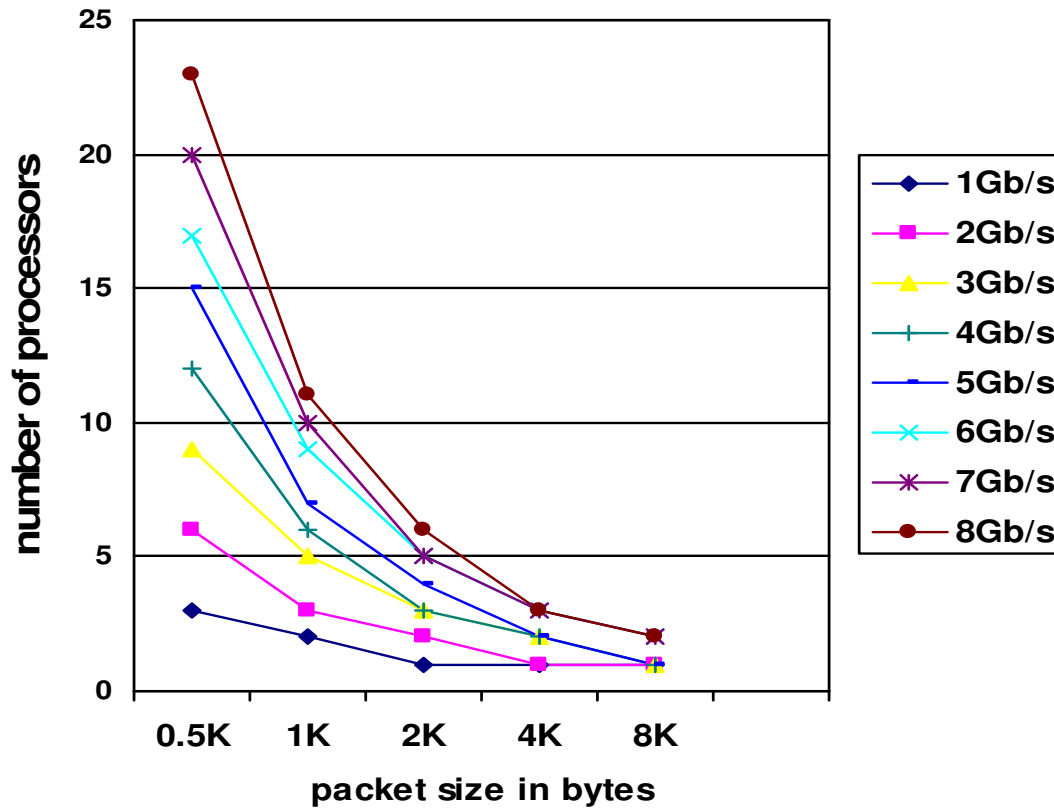
- **Multi Vt, clock gating, power gating**
- **Voltage islands, voltage and frequency scaling**
- **Asynchronous design**
- **Multiple cores**
- **Accelerators**
- **Memory hierarchy**
- **I/O network**
- **New packaging concepts**

Example - Multiprocessor Accelerator for SoC Design

- **Self-contained, scalable multiprocessor core**
 - With its own general-purpose processors, interconnect, interfaces and memory
- **Connected to the SoC bus via a bridge**
 - Easy integration in the basic SoC structure
- **Inner structure and complexity is hidden from the SoC designer**
 - Significantly simplifies the SoC design



Accelerator Performance and Floorplan

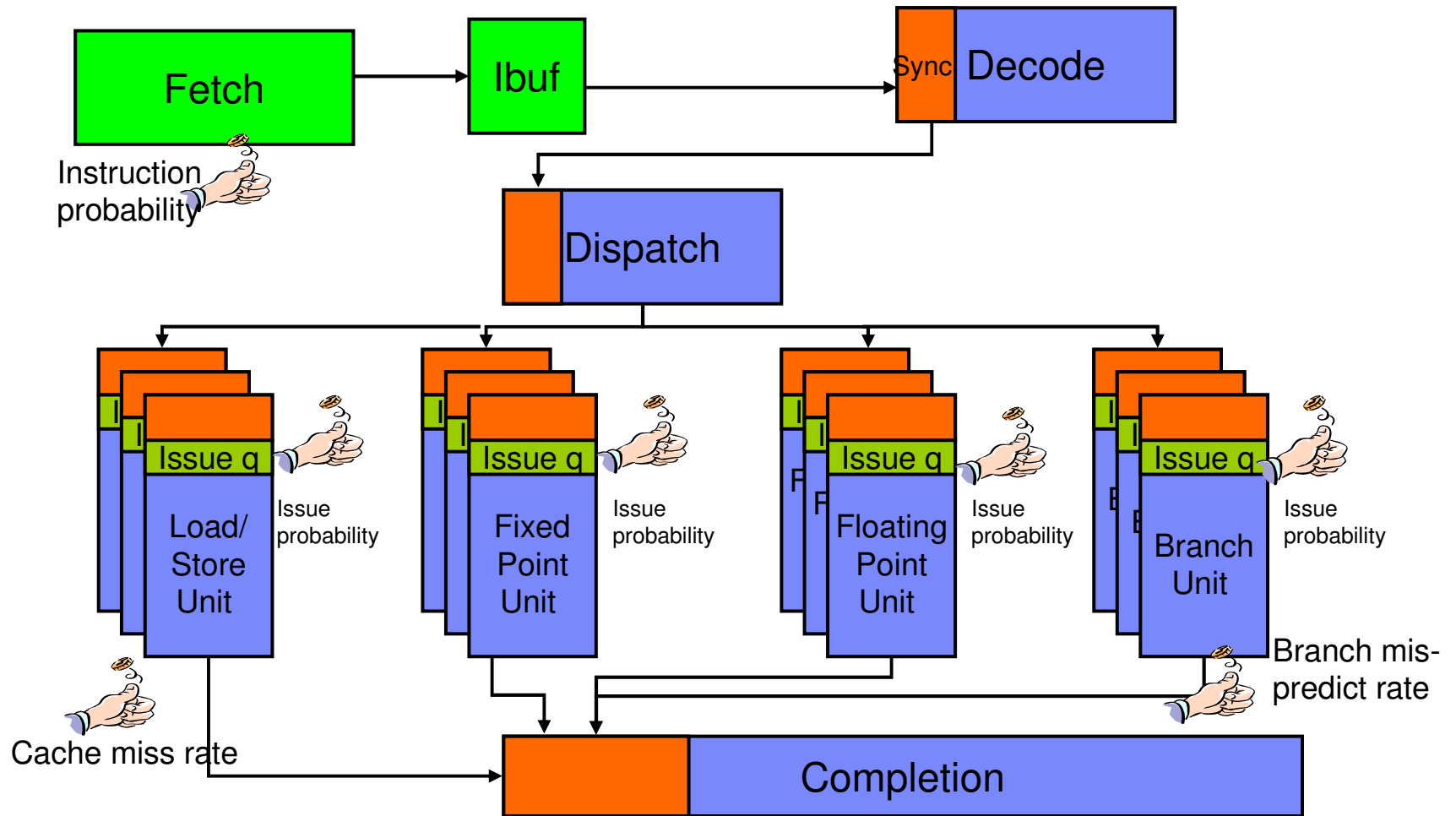


- Parametric core offers wide range of performance
- Need to evaluate novel architectures in system context

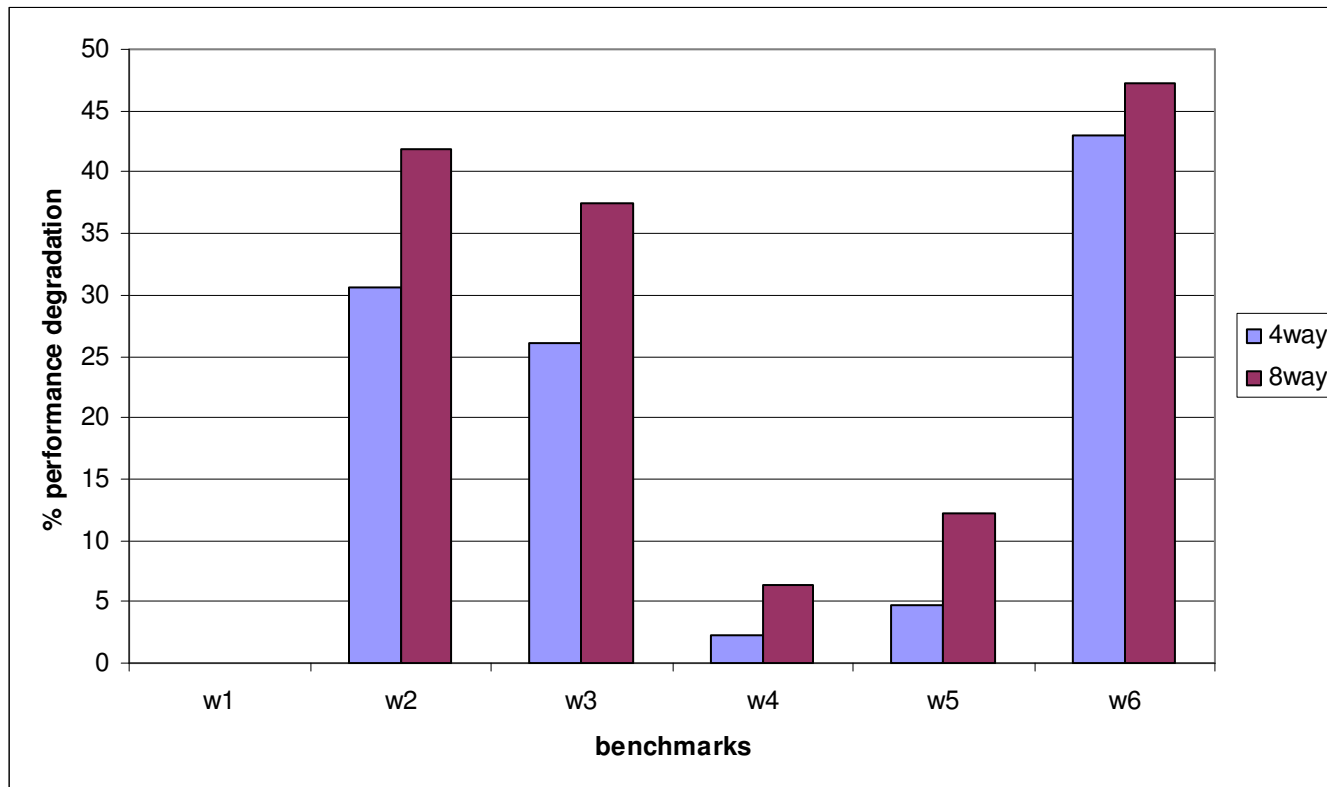
Globally Asynchronous Locally Synchronous - GALS

- **Voltage islands enable multiple frequency domains**
- **How many partitions?**
- **Where is best place to partition?**
- **What is synchronization penalty?**
- **Need flexible model to explore sensitivities**

GALS Example - Out of Order Machine



One GALS Experiment - Half the Fetch Frequency

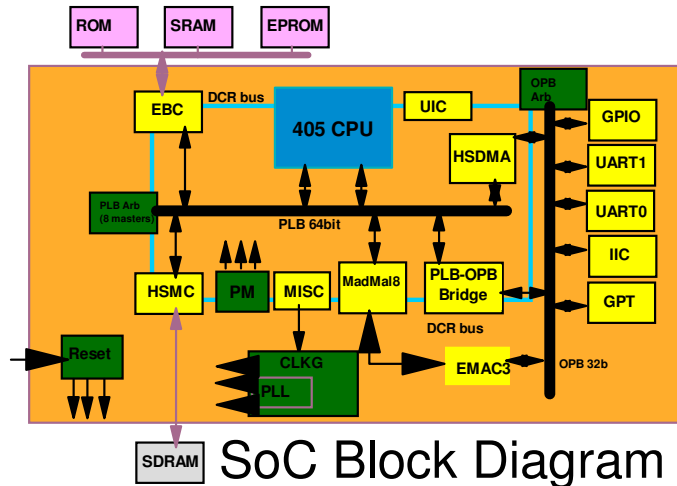


- Out-of-order machine, fetch clock 20ns, others 10ns, no sync penalty
- Compared with all units clocked at 10ns

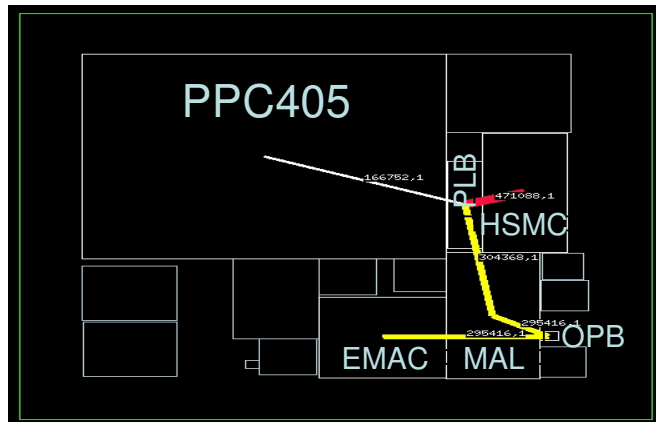
Need Tools to Evaluate Tradeoffs Early in Design

- **Intuitive design capture**
- **Unified representation above RTL**
- **Rapid and accurate tradeoff analysis**
 - Performance, power, interconnect
 - Handle technology options
 - Voltage Islands, multi-Vt, frequency scaling, clock gating
- **Linkage to RTL flow**

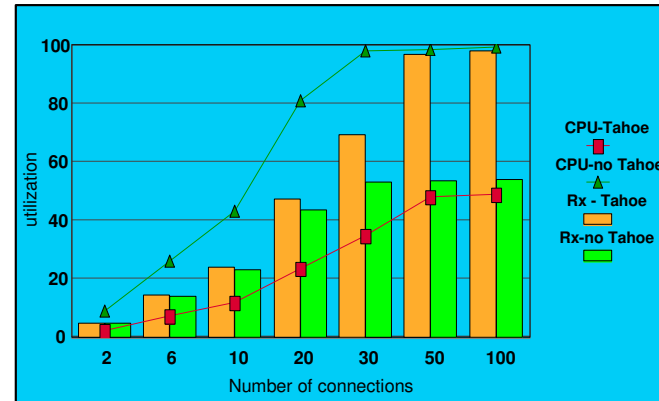
SEAS - SoC Early Analysis System



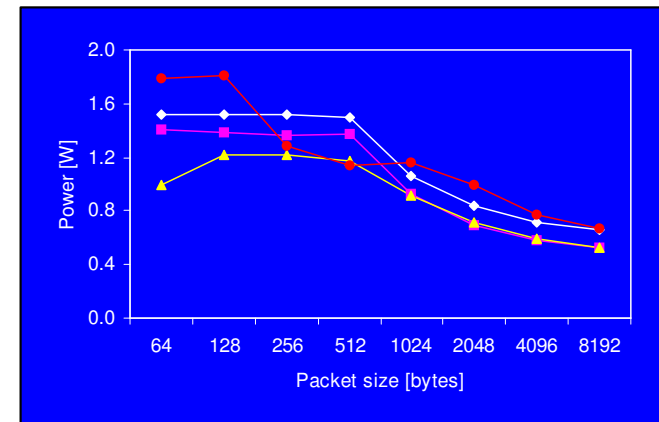
SoC Block Diagram



SoC Floorplan

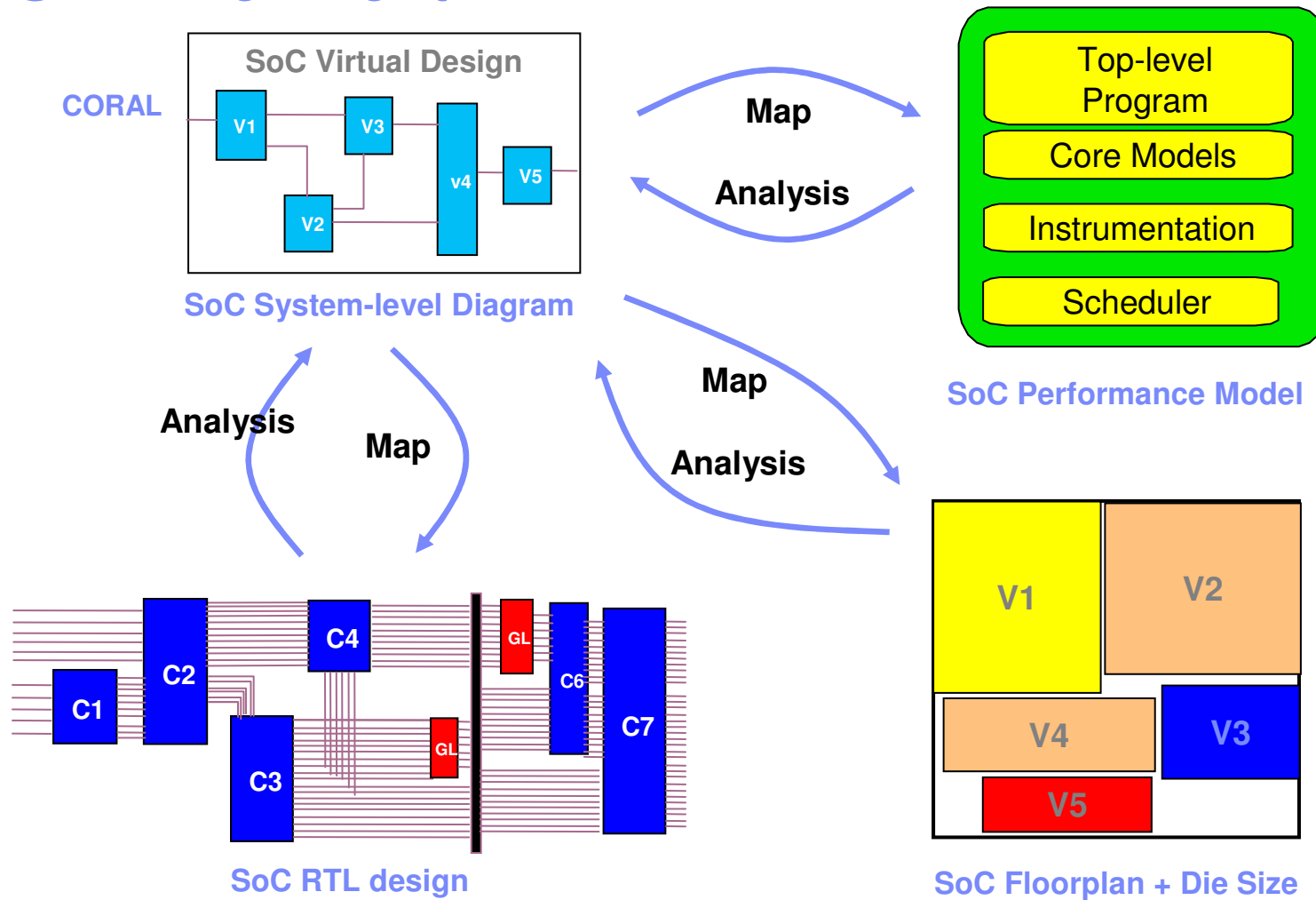


SoC Performance

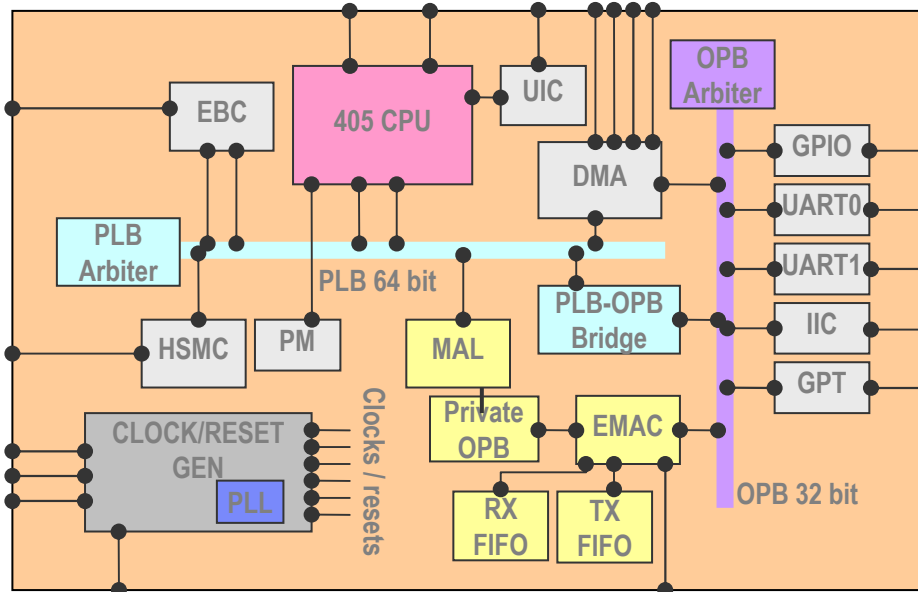


SoC Power

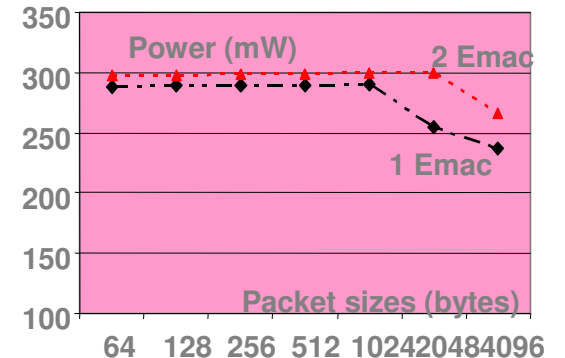
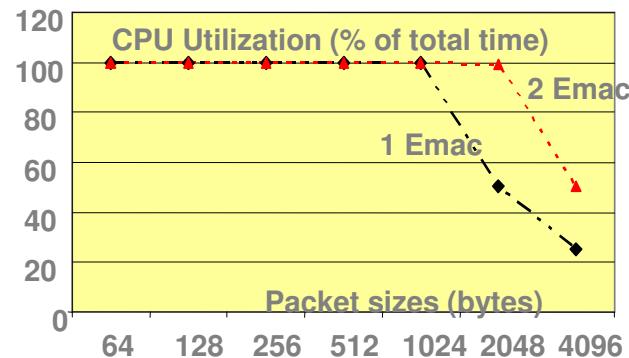
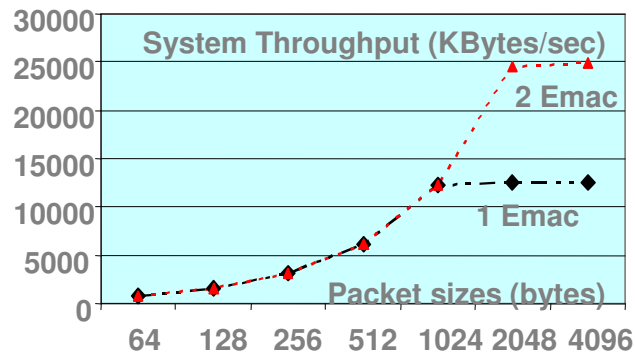
SEAS Environment



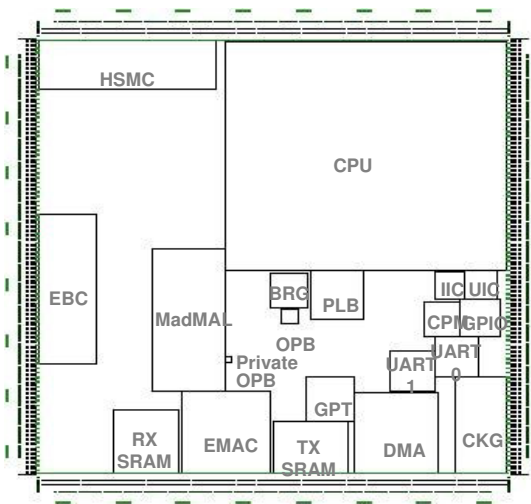
SEAS Experiment



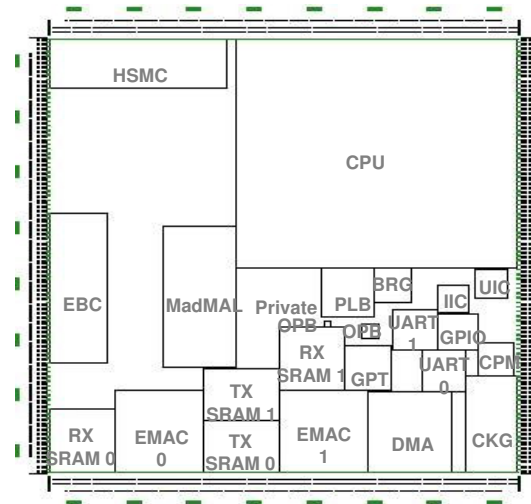
- **405 Platform**
 - Ethernet Subsystem
- **Add cores for capacity**
- **Assess Impact**
 - Performance
 - Power
 - Chip size



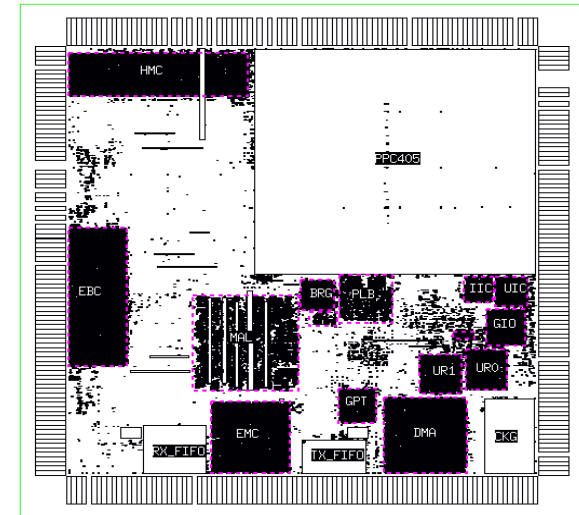
SEAS Experiment



1 EMAC
6.05mmx6.05mm



2 EMACs
6.05mmx6.05mm



Real Design Layout (1 EMAC)
6.05mmx6.05mm

Results

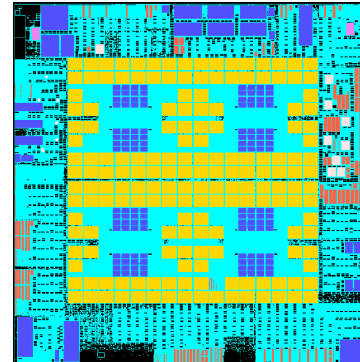
- Revised design met performance requirement
- Could fit in original die-size (pin limited)
- Floorplanned implementation met timing requirements

System Trends

- **Today's ASIC and processor design methodologies are distinct**
- **As technology enables greater integration they will converge**

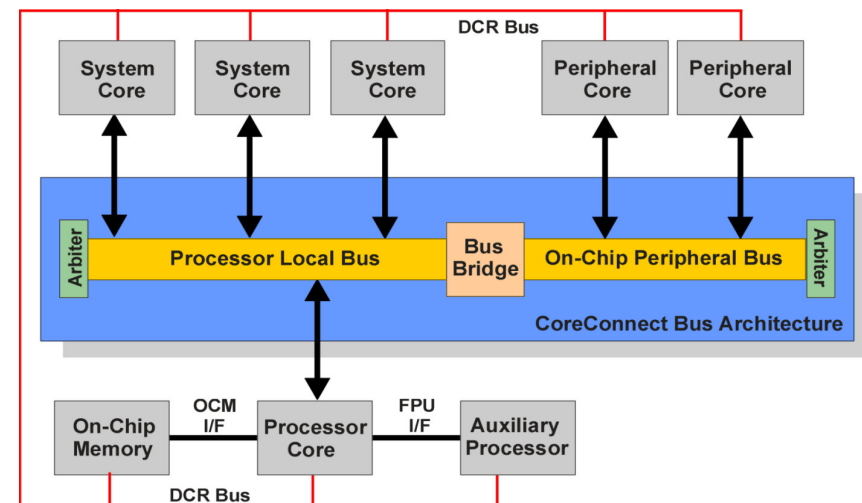
IBM ASIC Characteristics

- **Large chips**
 - 2X industry average
- **Rapid TAT**
- **First time right**
- **SoC approach**
 - Pre-verified reusable cores
 - Design at system level
 - Rapid implementation



40-Terabit Router Engine

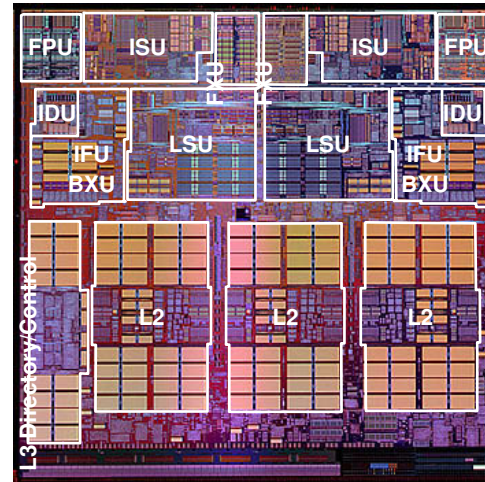
- 38 M gates
- 130 nm
- 18.3 mm x 18.3 mm
- 7 Levels of Metal
- 3389 Total I/O



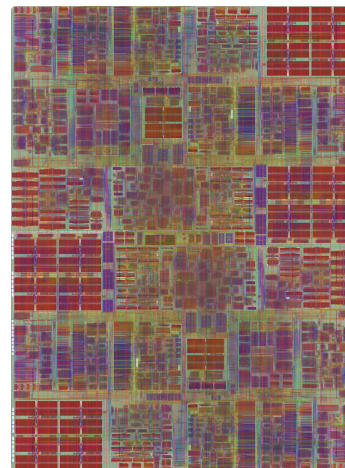
IBM Core Connect Architecture

IBM Processor Characteristics

- **Large chips**
- **Custom macros**
- **50% synthesized logic**
- **First to see challenges**
- **First time right**
- **Multi-core**
 - Increasing parallelism
 - More moving on chip

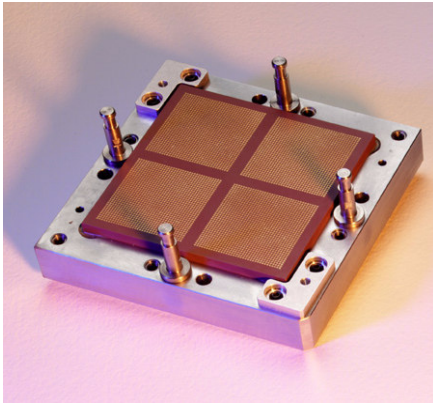


- **First dual-core CPU**
- **On-chip L2 & L3 dir**
- **~1.5 Ghz Frequency**
- **184M transistors**
- **180nm (2001)**
- **130nm (2002) SOI**



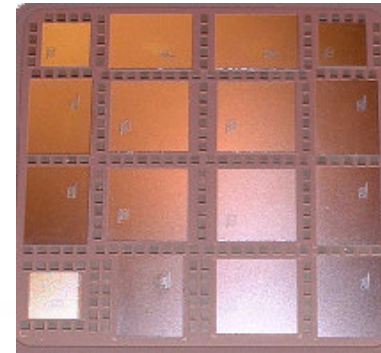
- **Dual core mainframe**
- **~1.2GHz (short pipeline)**
- **121M transistors**
- **130nm (2003) SOI**

IBM Server Characteristics



IBM pSeries

- P690 module
- 8-way with 4 chips
- 32-way system



IBM zSeries

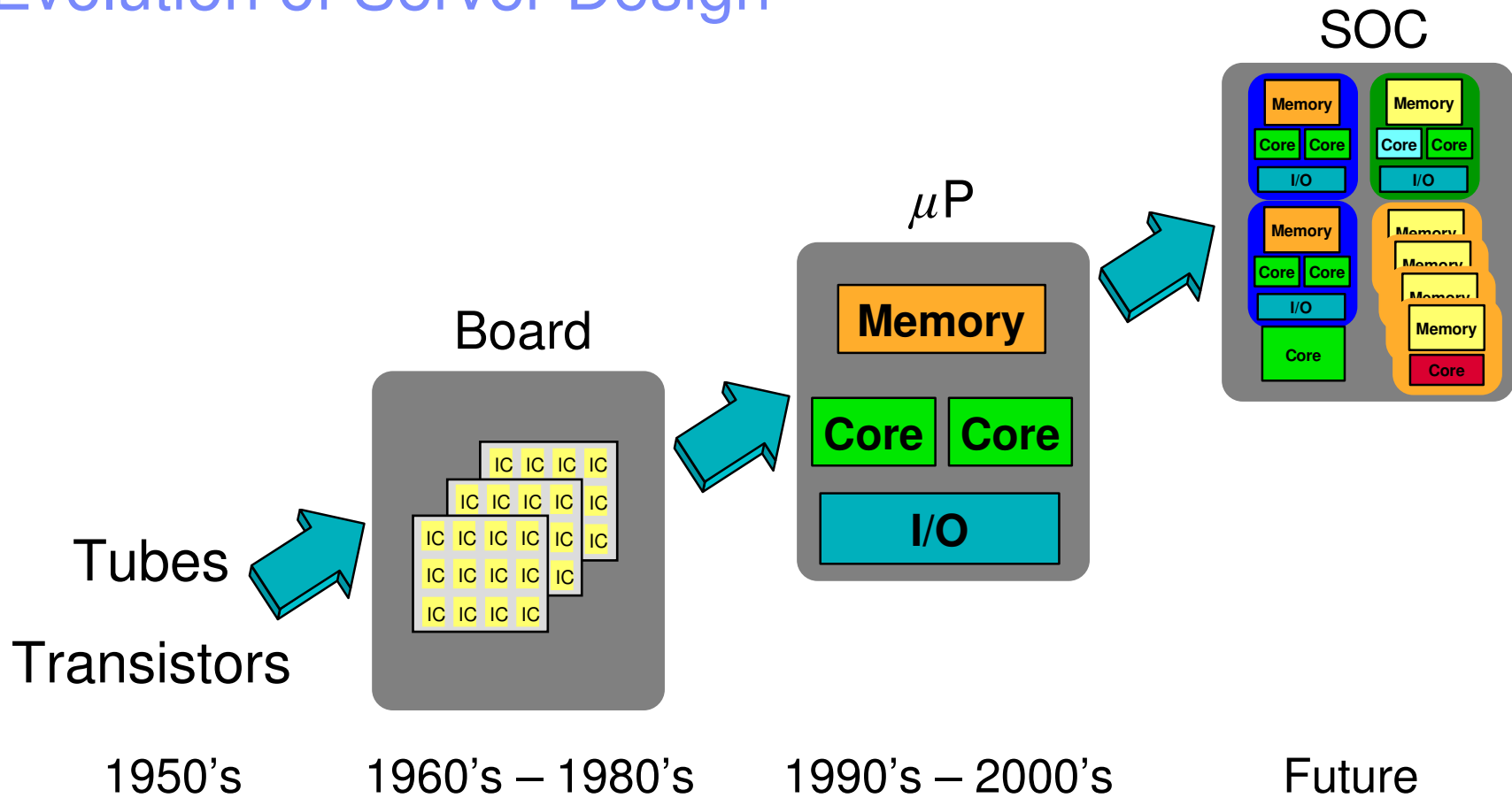
- 16-way module
- shared L2

- **Still more parallelism**
- **Will move to chip in future**



- 20 way Freeway 2000
- First 64-bit mainframe
- 64-way Trex 2003
- 4 16-way boards

Evolution of Server Design

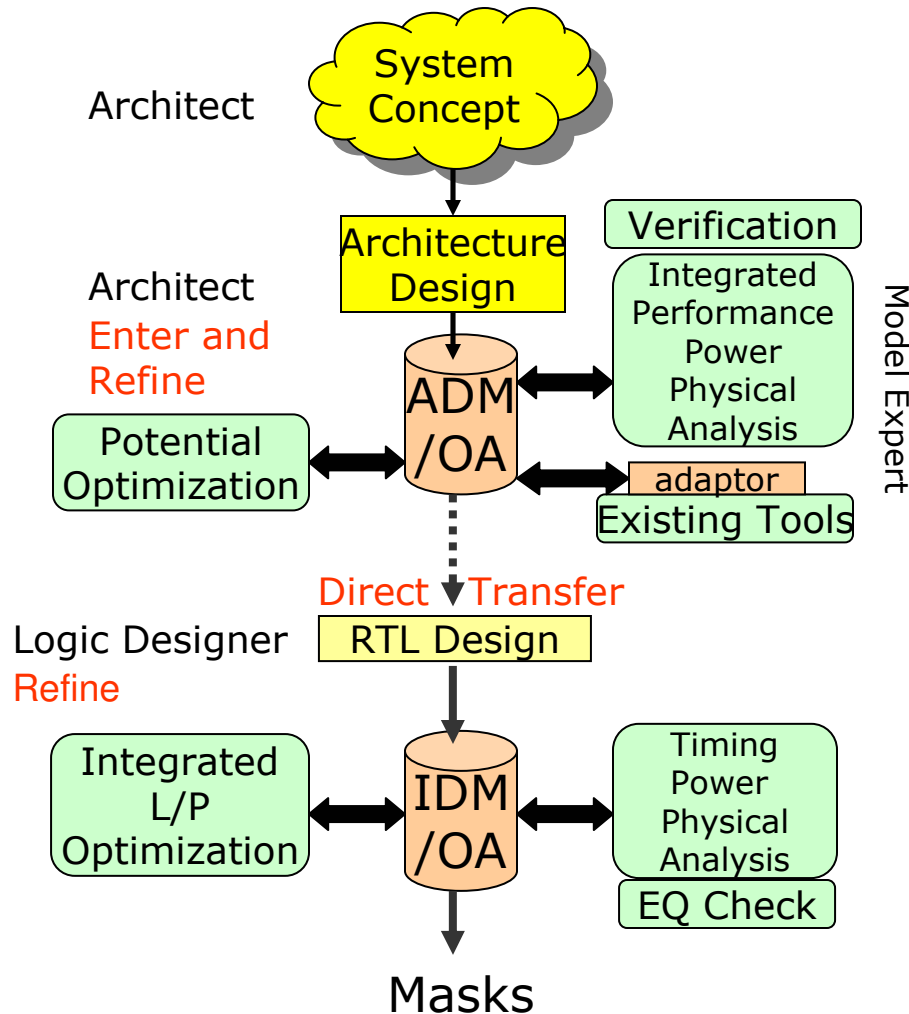


Future Server-on-a-Chip Methodology

- **System-level assembly of components**
- **Efficient custom design of key components**
- **Synthesis of non-custom components**
- **Accurate planning for power, interconnect, timing**
- **Automated chip integration – buffers, clocks, power**

- **Need to combine best of ASIC and processor methods**

Future System-Level Design System

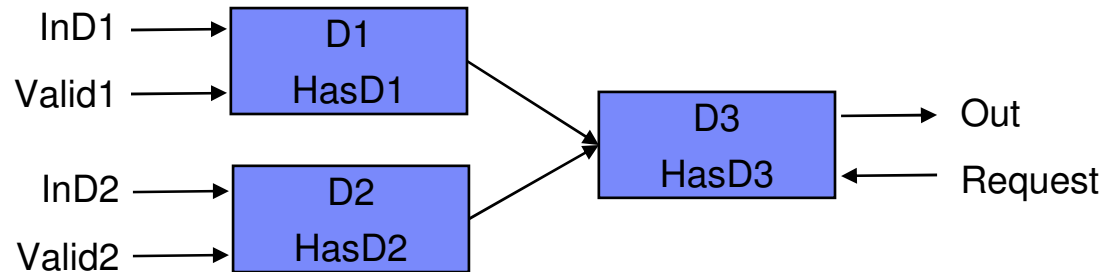


- **System-Level Representation**
- **Integrate power, performance and interconnect analysis**
- **Enable optimization**
- **Link to RTL Implementation**
 - **Accurate prediction**
 - **Accelerate implementation**
- **Verification**
 - **Prove key properties**
 - **Check implementation**
- **Extend Open Access to system level**
 - **Enable tight link to RTL**
 - **Stimulate system-level R&D**

Need System-Level Representation

- **Include all design factors**
 - Function, physical, power, thermal, reliability, ...
- **Accept diverse forms**
 - Functional, structural, assertions, constraints, ...
- **Support several levels of abstraction**
 - Yet enable verification between levels

System-Level Verification – Data Merger Example



5 Non-deterministic Rules

1. $|\neg\text{HasD1} \ \& \ \text{Valid1}| \rightarrow \{\text{D1}:=\text{InD1}; \text{HasD1}:=\text{true};\}$
2. $|\neg\text{HasD2} \ \& \ \text{Valid2}| \rightarrow \{\text{D2}:=\text{InD2}; \text{HasD2}:=\text{true};\}$
3. $|\text{HasD1} \ \& \ \neg\text{HasD3}| \rightarrow \{\text{D3}:=\text{D1}; \text{HasD1}:=\text{false}; \text{HasD3}:=\text{true};\}$
4. $|\text{HasD2} \ \& \ \neg\text{HasD3}| \rightarrow \{\text{D3}:=\text{D2}; \text{HasD2}:=\text{false}; \text{HasD3}:=\text{true};\}$
5. $|\text{Request} \ \& \ \text{HasD3}| \rightarrow \{\text{Out}:=\text{D3}; \text{HasD3}:=\text{false};\}$

System-Level Verification – Experiment

- **Specified Data Merger with Murphi and SystemC**
 - Independent rules simplify task
- **Proved data inputs not lost**
- **Implemented at gate level, VHDL and SystemC**
- **Proved implementation is refinement of specification**
- **Similar results for much larger distributed cache**
- **Greatly reduces proof complexity**

SUMMARY

- **Business demanding more innovative systems**
- **Technology pressuring other performance factors**
- **Systems calling for Server-on-a-Chip methodology**

- **Need to merge best of ASIC and processor methods**
- **Need to raise DA to system-level**
- **Standards can enable faster development**

First Integrated Design System Workshop

- **DAC – Monday, June 13, 2005 Anaheim, California**
- **Follow-on to 5 successful Interoperability Workshops**
- **Organizers**
 - John Darringer – IBM, Rahul Goyal - Intel,
 - Scott Peterson - LSI, Alva Barney – HP
- **Objective**
 - Integrated design systems are essential
 - Open Access is an enabler, but more is required
 - What else is needed for future design systems to keep pace?

Integrated Design System Workshop Agenda

1:00 Introduction John Darringer Research Manager, IBM

1:20 User Views Chair: Alva Barney, CAD Manager, HP

Siva Yerramilli, Dir. Design Technology, Intel

David Kung, Sr. Mgr, Design Automation, IBM

Lambert van den Hoven, VP Design Technology, Philips

Yoshi Inoue Group Manager Renesas

2:10 Vendor Views Chair: Rahul Goyal, Dir. EDA Business, Intel

Aurangzeb Khan, VP Design Foundries, Cadence

Eshel Haritan, VP Engineering, Co-Ware

Premal Buch, GM Design Implementation, Magma

Rich Goldman, VP Market Dev, Synopsys

Robert Hum, VP Design, Verification and Test, Mentor Graphics

3:00 Other Views Chair: Scott Peterson, Dir. Rapid Chip Methodology, LSI

Gary Smith, Chief Analyst, Gartner Dquest

Steve Schulz, CEO, Si2

Andreas Kuehlmann, Dir. Cadence Berkeley Labs

Jim Solomon, CEO Xulu Entertainment

3:45 Break

4:10 PANEL: What's Next? Chair: Richard Goering, Editor, EE Times

Acknowledgements

■ Referenced publications

- “Early Analysis Tools for System-on-a-Chip Design”, J Darringer, R. Bergamaschi, S. Bhaatacharya, D. Brand, A. Herkersdorf, J. Morrell, I. Nair, P. Sagmeister and Y. Shin, IBM JR&D Vol 46, No 6., Nov. 2002
- “SEAS: A System for Early Analysis of SoCs”, R. Bergamaschi, Y. Shin, N. Dhanwada, S. Bhaatacharya, W. Dougherty, I. Nair, J. Darringer, S. Paliwal, CODES-ISSS 2003
- “Formal Verification of Distributed Cache Memory Protocols”, S. German, FMCAD 2004
- “Understanding Basic Tradeoffs in Multiple Frequency Processor Core Micro-architectures through a Statistical Timing Model”, I. Nair, A. Buyuktosunoglu, internal paper
- “An efficient System-on-a-Chip Design methodology for Networking applications”, V. Salapura, C. Georgiou and I. Nair, CASES '04

■ Plus discussions with

- Jeff Welser, Erik Kronstadt, Jaime Moreno,